CLAIMS

1. A conductive composition for bonding, comprising a copper powder and a carboxylic acid mixed therewith,

wherein

the carboxylic acid has a branched carbon chain in its structure,

the copper powder comprises first copper particles and second copper particles, wherein,

the first copper particles have a volume-based cumulative particle size D_{50} of 0.11 μm or more and less than 1 μm at a cumulative volume of 50 vol% in a region of particle sizes of less than 1 μm in a particle size distribution of the copper powder that is determined using a scanning electron microscope, and

the second copper particles have a volume-based cumulative particle size D_{50} of 1 μm or more and 10 μm or less at a cumulative volume of 50 vol% in a region of particle sizes of 1 μm or more in the particle size distribution of the copper powder that is determined using the scanning electron microscope, and

the carboxylic acid is contained in an amount of 6 parts by mass or more and 24 parts by mass or less per 100 parts by mass of the copper powder, and

the percentage of the first copper particles is 30 to 95 mass%, based on a total mass of the first and second copper particles.

2. The conductive composition for bonding as set forth in claim 1, wherein the carboxylic acid is an aliphatic monovalent carboxylic acid having 4 to 18 carbon atoms.

3. The conductive composition for bonding as set forth in claim 1 or 2, wherein the carboxylic acid is a tertiary carboxylic acid.

4. The conductive composition for bonding as set forth in any one of claims 1 to 3, wherein the carboxylic acid is liquid at 1 atm and 20°C.

5. The conductive composition for bonding as set forth in any one of claims 1 to 4,

wherein the carboxylic acid is neodecanoic acid.

6. A bonded structure comprising a first conductor, a second conductor, and a bonding portion with which the first conductor and the second conductor are bonded to each other,

wherein the bonding portion comprises a sintered body of the conductive composition for bonding as set forth in any one of claims 1 to 5.

7. A method for producing a bonded structure, comprising

a step of interposing the conductive composition for bonding as set forth in any one of claims 1 to 5 between two conductors, and

a step of sintering the conductive composition for bonding.